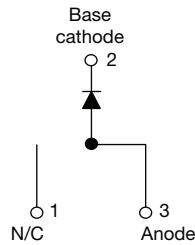


## High Performance Schottky Rectifier, 19 A


**D<sup>2</sup>PAK**


### FEATURES

- 125 °C T<sub>J</sub> operation (V<sub>R</sub> < 5 V)
- Optimized for OR-ing applications
- Ultralow forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

### PRODUCT SUMMARY

Package	D <sup>2</sup> PAK
I <sub>F(AV)</sub>	19 A
V <sub>R</sub>	15 V
V <sub>F</sub> at I <sub>F</sub>	0.36 V
I <sub>RM</sub> max.	522 mA at 100 °C
T <sub>J</sub> max.	125 °C
Diode variation	Single die
E <sub>AS</sub>	6.75 mJ

### DESCRIPTION

The VS-19TQ015SPbF Schottky rectifier has been optimized for ultralow forward voltage drop specifically for the OR-ing of parallel power supplies. The proprietary barrier technology allows for reliable operation up to 125 °C junction temperature. Typical applications are in parallel switching power supplies, converters, reverse battery protection, and redundant power subsystems.

### MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
I <sub>F(AV)</sub>	Rectangular waveform	19	A
V <sub>RRM</sub>		15	V
I <sub>FSM</sub>	t <sub>p</sub> = 5 μs sine	700	A
V <sub>F</sub>	19 A <sub>pk</sub> , T <sub>J</sub> = 75 °C	0.32	V
T <sub>J</sub>	Range	-55 to +125	°C

### VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-19TQ015SPbF	UNITS
Maximum DC reverse voltage	V <sub>R</sub>	15	V
Maximum working peak reverse voltage	V <sub>RWM</sub>		

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current See fig. 5	I <sub>F(AV)</sub>	50 % duty cycle at T <sub>C</sub> = 80 °C, rectangular waveform	19	A
Maximum peak one cycle non-repetitive surge current See fig. 7	I <sub>FSM</sub>	5 μs sine or 3 μs rect. pulse	700	A
		10 ms sine or 6 ms rect. pulse	330	
Non-repetitive avalanche energy	E <sub>AS</sub>	T <sub>J</sub> = 25 °C, I <sub>AS</sub> = 1.50 A, L = 6 mH	6.75	mJ
Repetitive avalanche current	I <sub>AR</sub>	Current decaying linearly to zero in 1 μs Frequency limited by T <sub>J</sub> maximum V <sub>A</sub> = 3 x V <sub>R</sub> typical	1.50	A

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	19 A	$T_J = 25\text{ }^\circ\text{C}$	0.36	V
		38 A		0.46	
		19 A	$T_J = 75\text{ }^\circ\text{C}$	0.32	
		38 A		0.43	
Maximum reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 100\text{ }^\circ\text{C}, V_R = 12\text{ V}$		465	mA
		$T_J = 100\text{ }^\circ\text{C}, V_R = 5\text{ V}$		285	
		$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	10.5	
		$T_J = 100\text{ }^\circ\text{C}$		522	
Maximum junction capacitance	$C_T$	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^\circ\text{C}$		2000	pF
Typical series inductance	$L_S$	Measured lead to lead 5 mm from package body		8.0	nH
Maximum voltage rate of change	dV/dt	Rated $V_R$		10 000	V/ $\mu\text{s}$

**Note**

(1) Pulse width < 300  $\mu\text{s}$ , duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction temperature range	$T_J$			-55 to +125	$^\circ\text{C}$
Maximum storage temperature range	$T_{Stg}$			-55 to +150	
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation See fig. 4		1.50	$^\circ\text{C/W}$
Typical thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, smooth and greased		0.50	
Approximate weight				2	g
				0.07	oz.
Mounting torque	minimum			6 (5)	kgf · cm (lbf · in)
	maximum			12 (10)	
Marking device		Case style D <sup>2</sup> PAK		19TQ015S	

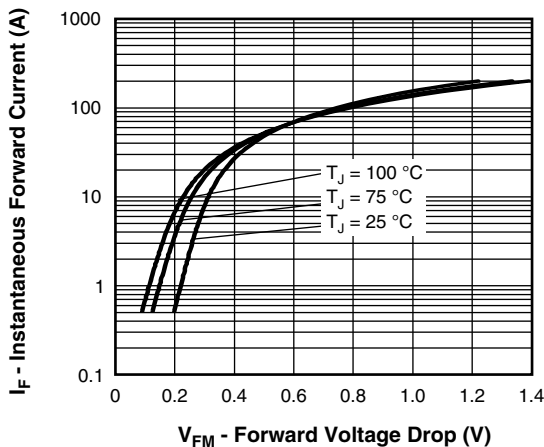


Fig. 1 - Maximum Forward Voltage Drop Characteristics

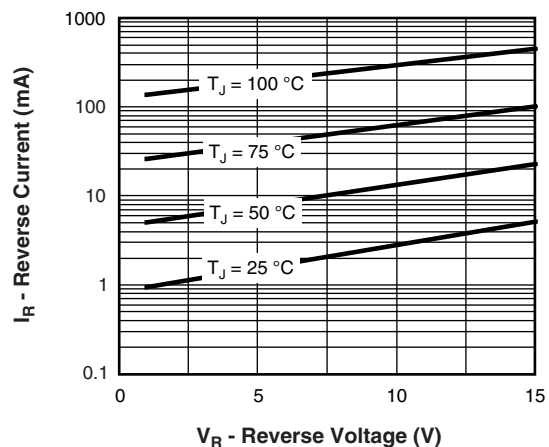


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

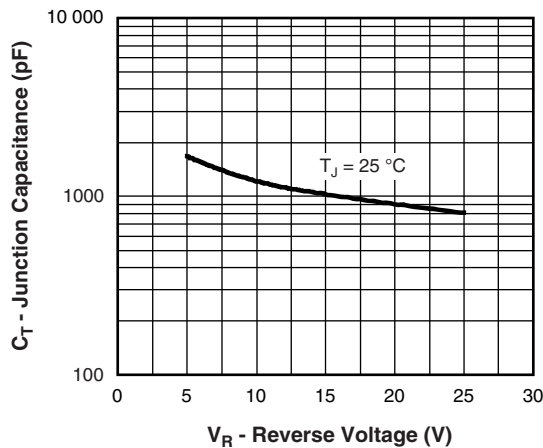


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

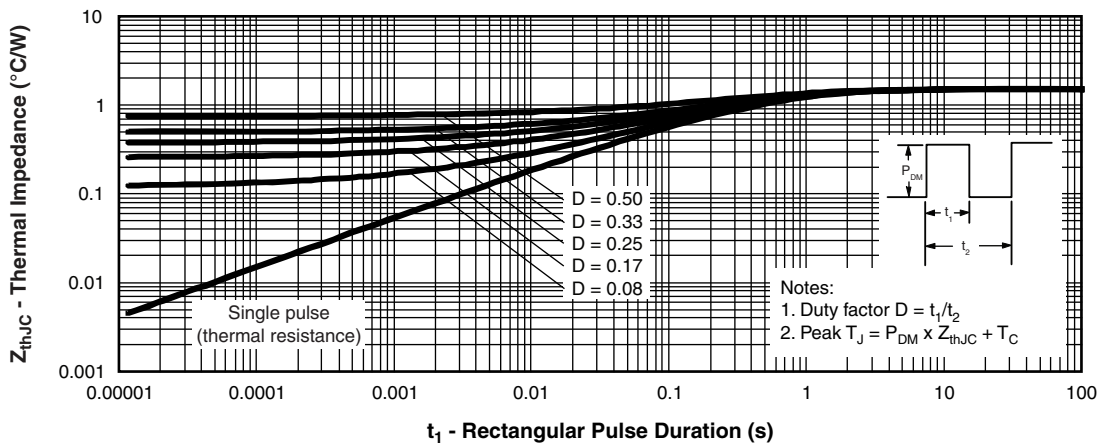


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

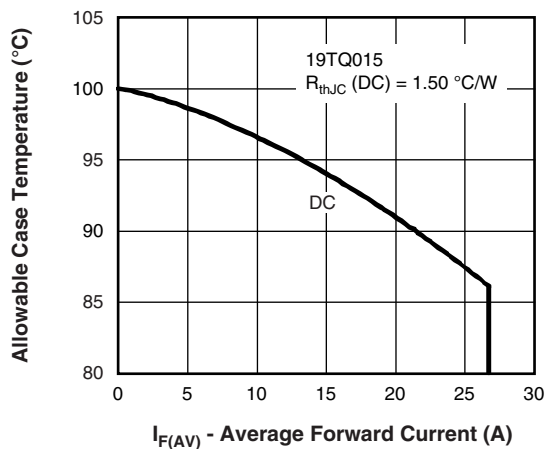


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

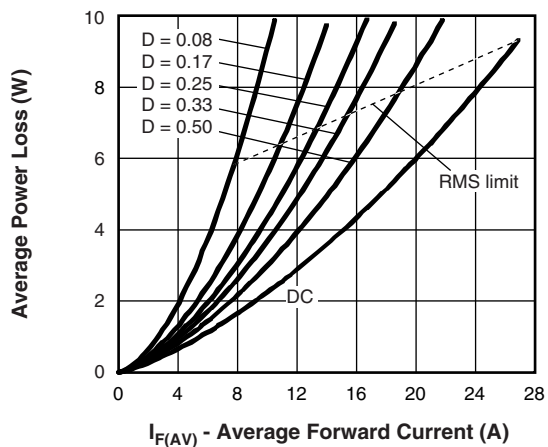


Fig. 6 - Forward Power Loss Characteristics

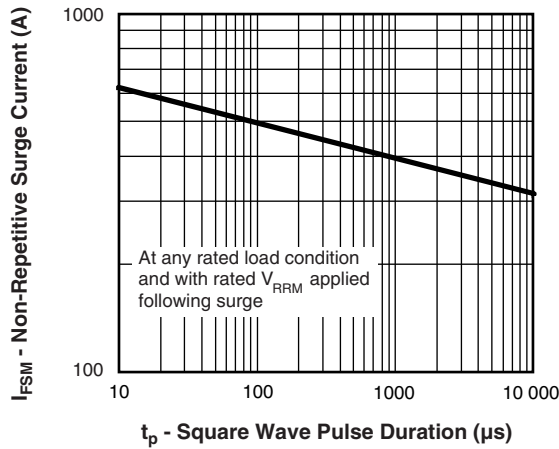


Fig. 7 - Maximum Non-Repetitive Surge Current

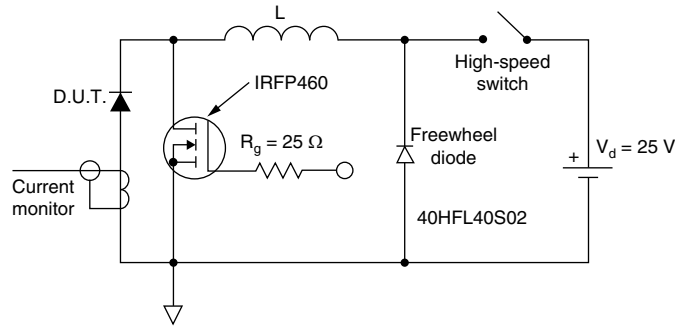


Fig. 8 - Unclamped Inductive Test Circuit

**ORDERING INFORMATION TABLE**

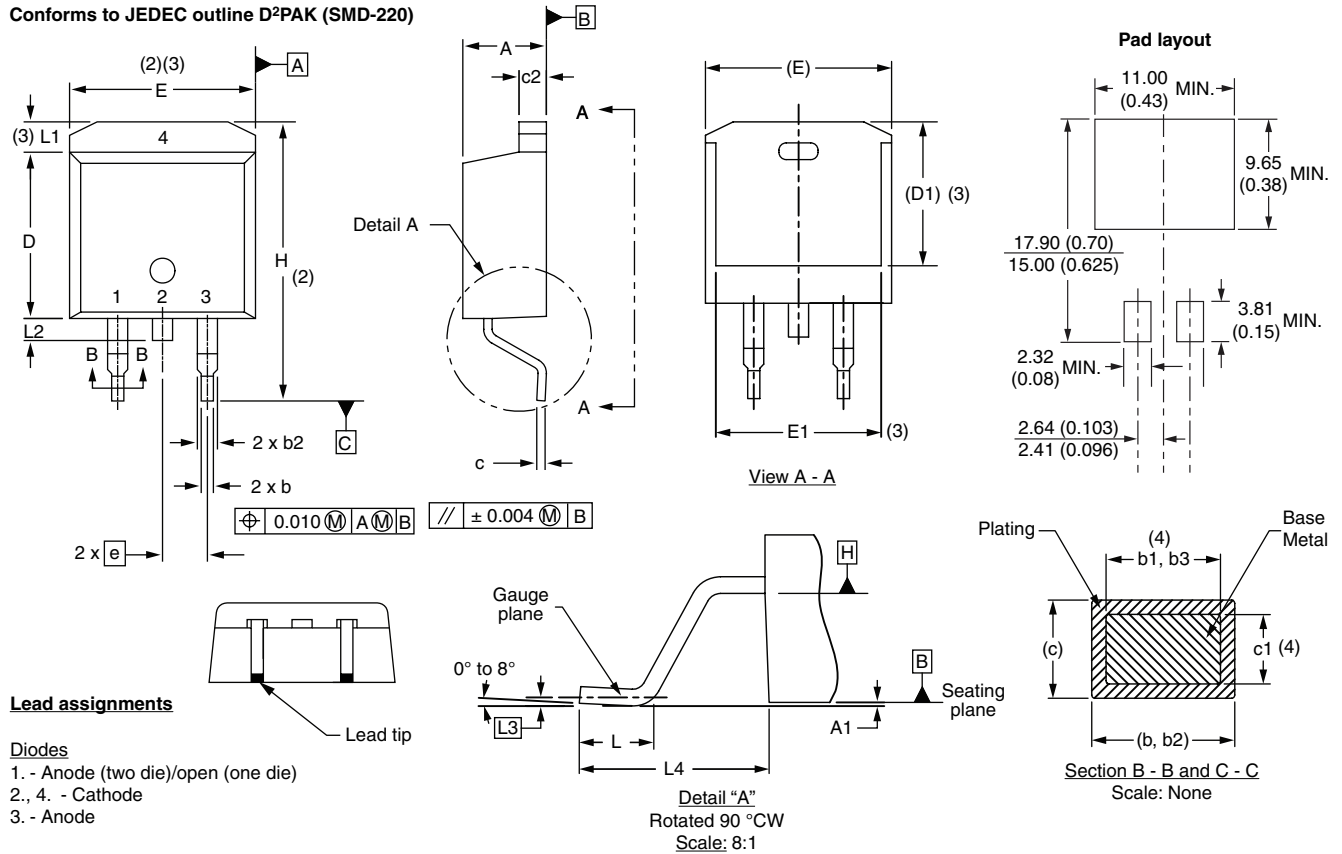
Device code	<b>VS-</b>	<b>19</b>	<b>T</b>	<b>Q</b>	<b>015</b>	<b>S</b>	<b>TRL</b>	<b>PbF</b>
	1	2	3	4	5	6	7	8
	1	2	3	4	5	6	7	8

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95014">www.vishay.com/doc?95014</a>
Part marking information	<a href="http://www.vishay.com/doc?95008">www.vishay.com/doc?95008</a>
Packaging information	<a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a>
SPIICE model	<a href="http://www.vishay.com/doc?96005">www.vishay.com/doc?96005</a>

## D<sup>2</sup>PAK, TO-262

### DIMENSIONS FOR D<sup>2</sup>PAK in millimeters and inches

Conforms to JEDEC outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

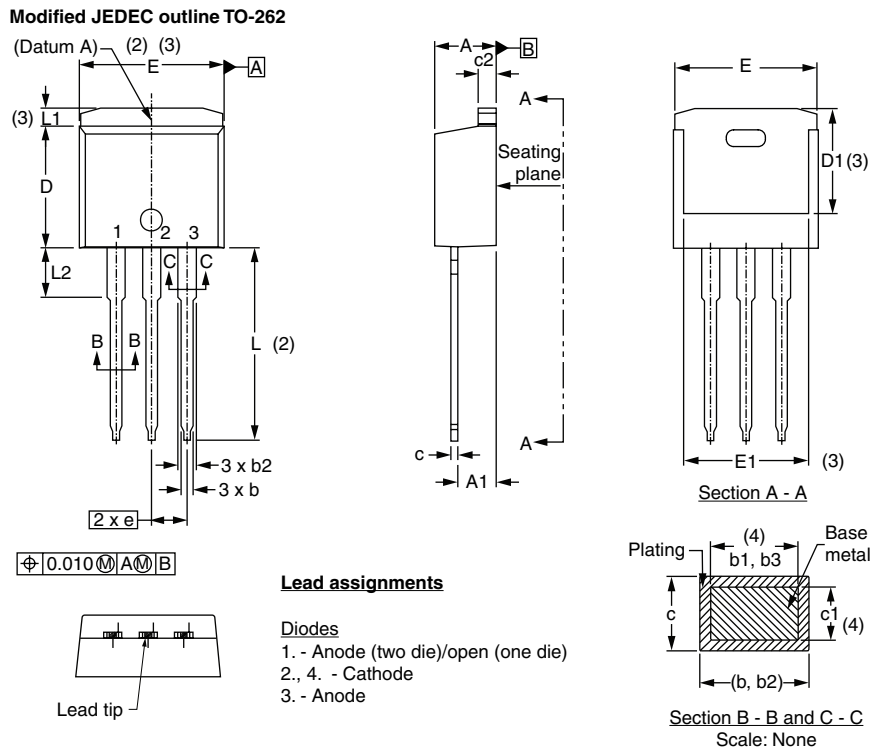
SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

- (7) Outline conforms to JEDEC outline TO-263AB

## DIMENSIONS FOR TO-262 in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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